



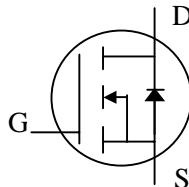
## N-channel Enhancement-mode Power MOSFET

**Simple Drive Requirement**

**Low On-resistance**

**Fast Switching Performance**

**RoHS-compliant, halogen-free**

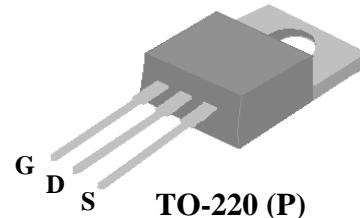


$BV_{DSS}$	120V
$R_{DS(ON)}$	8.5mΩ
$I_D$	130A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP92T12GP-HF-3 is in the TO-220 through-hole package which is used where a low PCB footprint or an attached heatsink is required.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	120	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$ at $T_C=25^\circ\text{C}$	Continuous Drain Current (Chip)	130	A
$I_D$ at $T_C=25^\circ\text{C}$	Continuous Drain Current <sup>3</sup>	120	A
$I_D$ at $T_C=100^\circ\text{C}$	Continuous Drain Current	95	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	300	A
$P_D$ at $T_C=25^\circ\text{C}$	Total Power Dissipation	375	W
$P_D$ at $T_A=25^\circ\text{C}$	Total Power Dissipation	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	0.4	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	62	°C/W

## Ordering Information

**AP92T12GP-HF-3TB    RoHS-compliant halogen-free TO-220, shipped in tubes (50pcs/tube)**



**Electrical Specifications at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	120	-	-	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=30\text{A}$	-	-	8.5	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	2	-	5	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=30\text{A}$	-	62	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=96\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	25	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$Q_{\text{g}}$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=30\text{A}$	-	97	155	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=96\text{V}$	-	27	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=10\text{V}$	-	48	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=60\text{V}$	-	27	-	ns
$t_{\text{r}}$	Rise Time	$I_{\text{D}}=30\text{A}$	-	96	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_{\text{G}}=3.3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	42	-	ns
$t_{\text{f}}$	Fall Time	$R_{\text{D}}=2\Omega$	-	60	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	4600	7360	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	800	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	260	-	pF
$R_{\text{g}}$	Gate Resistance	f=1.0MHz	-	2	-	$\Omega$

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=30\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.3	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=10\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	80	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	260	-	nC

**Notes:**

1. Pulse width limited by maximum junction temperature.
2. Pulse test
3. Package limitation current is 120A

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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## Typical Electrical Characteristics

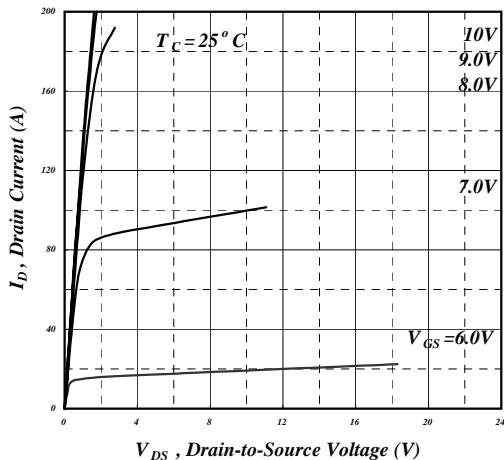


Fig 1. Typical Output Characteristics

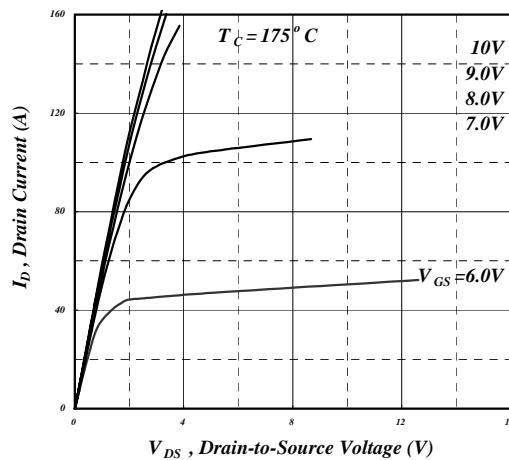


Fig 2. Typical Output Characteristics

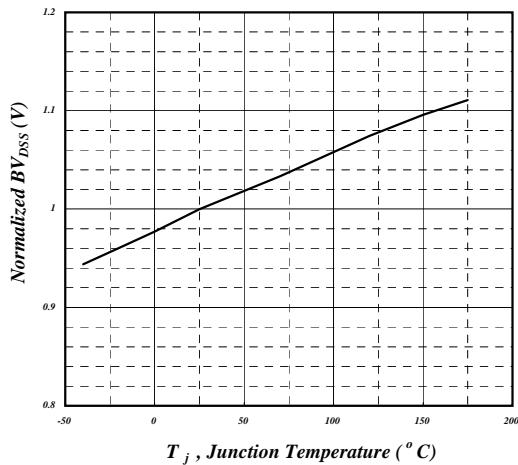


Fig 3. Normalized  $BV_{DSS}$   
vs. Junction Temperature

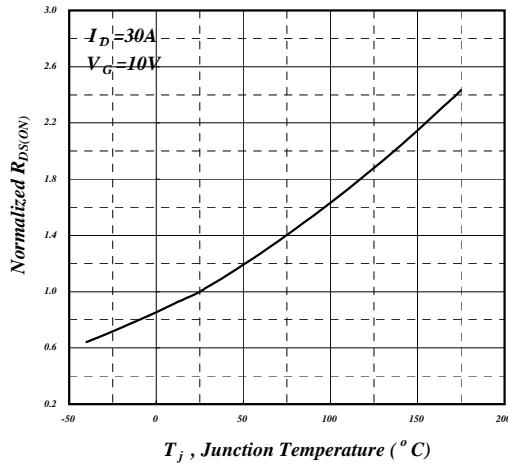


Fig 4. Normalized On-Resistance  
vs. Junction Temperature

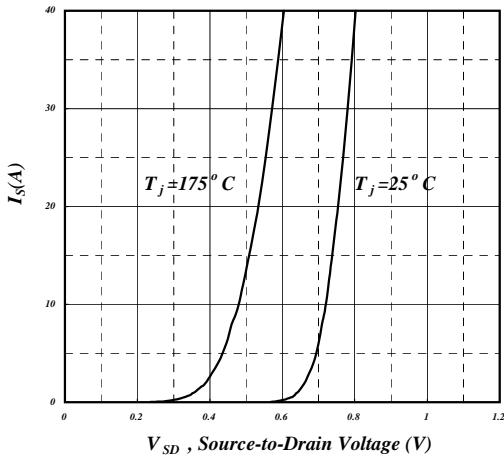


Fig 5. Forward Characteristic of  
Reverse Diode

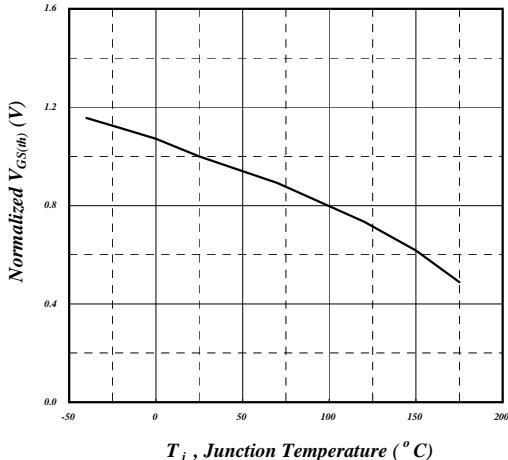


Fig 6. Gate Threshold Voltage v.s.  
Junction Temperature



## Typical Electrical Characteristics (cont.)

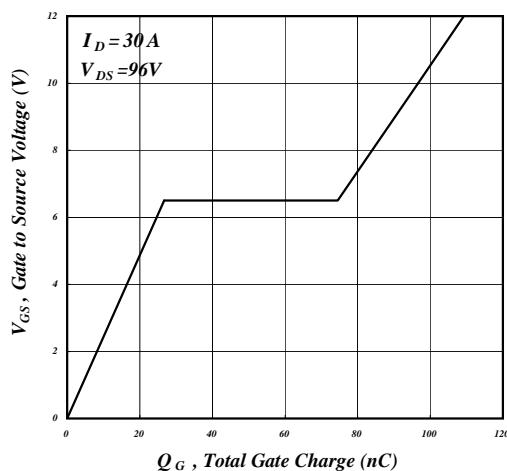


Fig 7. Gate Charge Characteristics

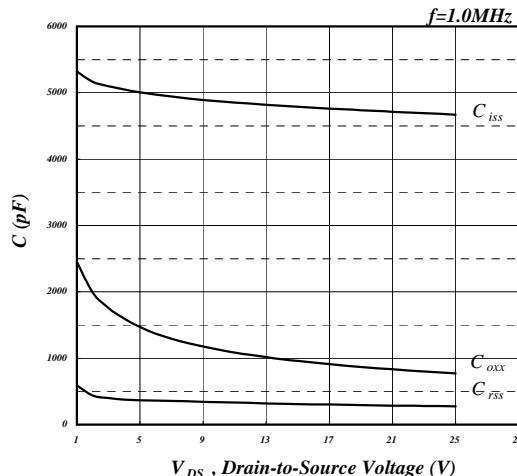


Fig 8. Typical Capacitance Characteristics

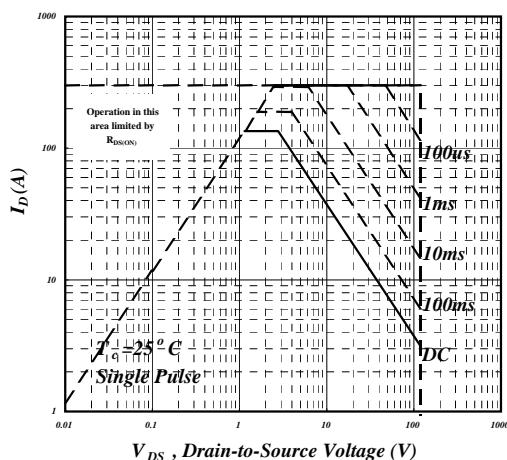


Fig 9. Maximum Safe Operating Area

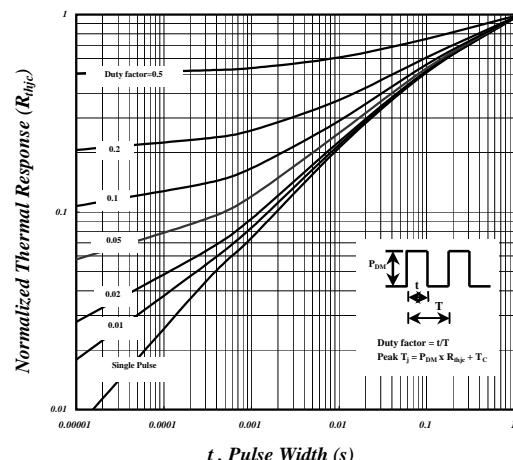


Fig 10. Effective Transient Thermal Impedance

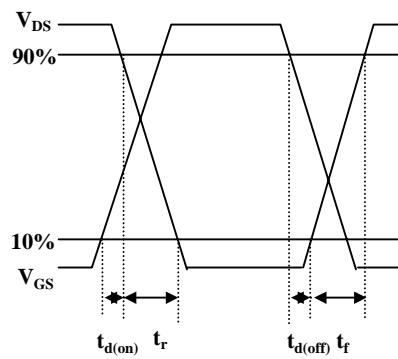


Fig 11. Switching Time Waveform

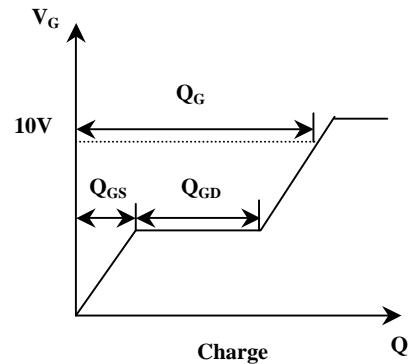
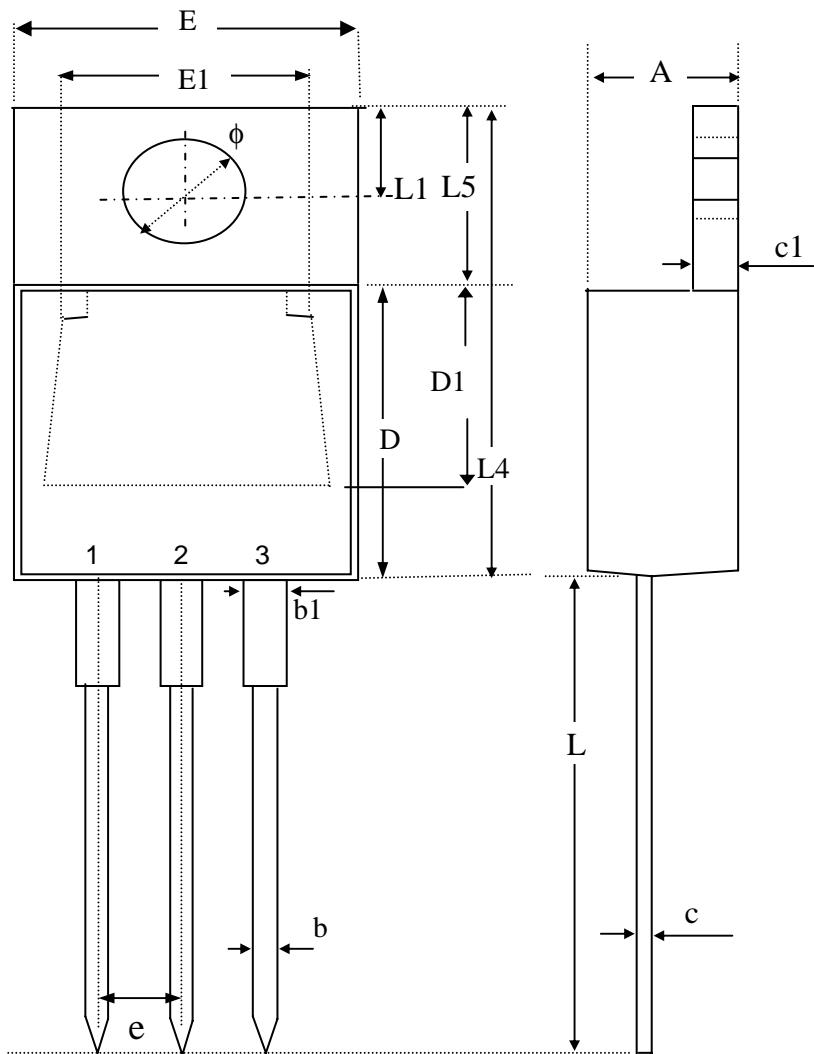


Fig 12. Gate Charge Waveform



## Package Dimensions: TO-220



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.40	4.60	4.80
b	0.76	0.88	1.00
D	8.60	8.80	9.00
c	0.36	0.43	0.50
E	9.80	10.10	10.40
L4	14.70	15.00	15.30
L5	6.20	6.40	6.60
D1	5.10 REF.		
c1	1.25	1.35	1.45
b1	1.17	1.32	1.47
L	13.25	13.75	14.25
e	2.54 REF.		
L1	2.60	2.75	2.89
φ	3.71	3.84	3.96
E1	7.4 REF,		

1. All dimensions are in millimeters.

2. Dimensions do not include mold protrusions.

## Marking Information: TO-220

